

Notice of References CitedApplication/Control No.
09/523,491Applicant(s)/Patent Under
Reexamination
KLAUS ET AL.Examiner
Eric B FullerArt Unit
1762

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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.